Robust High-Temperature Heat Exchangers (Topic 2A Gen 3 CSP Project; DE-EE0008369)



Illustrations of: (left) porous WC preform plates, (middle) dense-wall ZrC/W plates with horizontal channels and vertical vias. (Right) Backscattered electron image of the dense microstructure of a ZrC/W cermet.

Team: Ken H. Sandhage¹ (PI), Kevin P. Trumble¹ (Co-PI), Asegun Henry² (Co-PI), Aaron Wildberger³ (Co-PI)

¹School of Materials Engineering, Purdue University, W. Lafayette, IN

²Department of Mechanical Engineering, Massachusetts Institute of Technology, Cambridge, MA

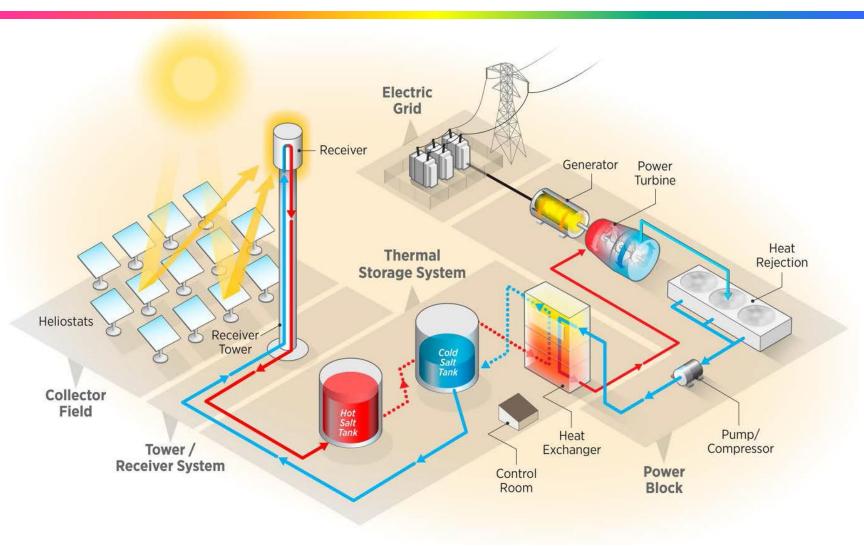
³Vacuum Process Engineering, Inc., Sacramento, CA





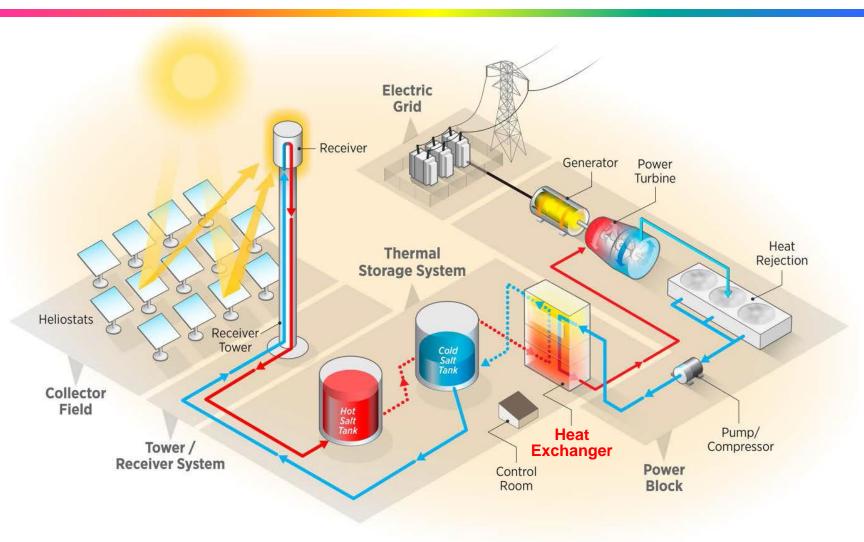


Concentrated Solar Power Tower



"Concentrating Solar Power Gen3 Demonstration Roadmap," M. Mehos, C. Turchi, J. Vidal, M. Wagner, Z. Ma, C. Ho, W. Kolb, C. Andraka, A. Kruizenga, Technical Report NREL/TP-5500-67464, National Renewable Energy Laboratory, 2017

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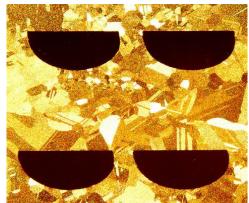
State of the Art: Metal Alloy Printed Circuit HEXs





D. Southall, S.J. Dewson, *Proc. ICAPP '10*, San Diego, CA, 2010; R. Le Pierres, et al., *Proc. SCO₂ Power Cycle Symposium 2011*, Boulder, CO, 2011; D. Southall, et al., *Proc. ICAPP '08*, Anaheim, CA, 2008.

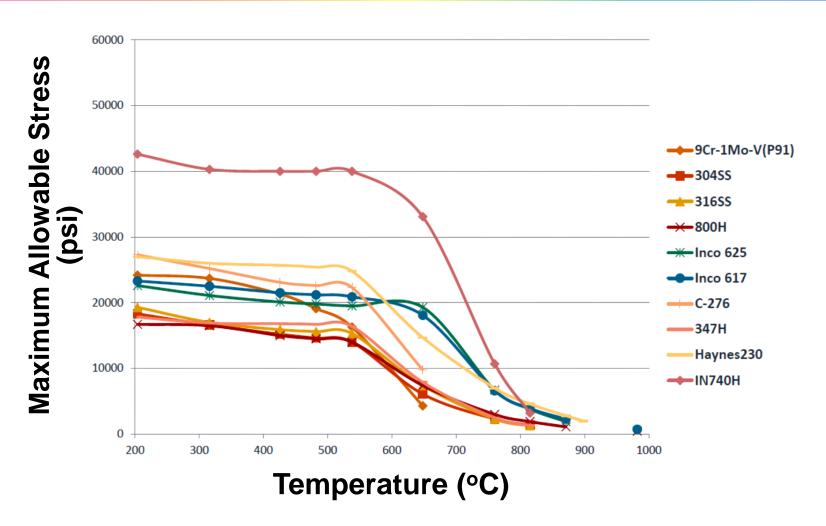




Current Technology:

- Printed Circuit HEXs: patterned etching of metallic alloy plates, then diffusion bonding
- Metal alloy mechanical properties degrade significantly above 600°C

State of the Art: Metal Alloy Printed Circuit HEXs



2010 ASME Boiler Pressure Vessel Code, Sec. II, from Tables 1A and 1B, July 1, 2010, New York, NY (compiled by Mark Anderson)

An Attractive Alternative: Compact Cermet HEXs





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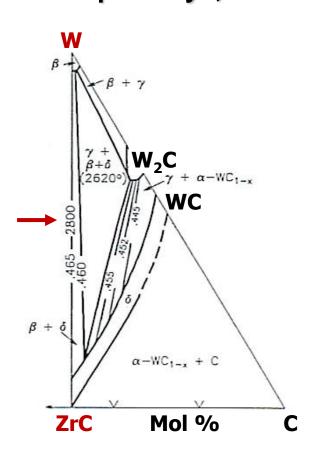
Current Technology:

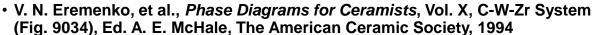
- Printed Circuit HEXs: patterned etching of metallic alloy plates, then diffusion bonding
- Metal alloy mechanical properties degrade significantly above 600°C

New Technology*:

- ZrC/W HEXs: mechanical forming of channeled porous WC plates, conversion into dense netsize ZrC/W plates, then diffusion bonding
- Higher stiffness, strength, and thermal conductivity at > 720°C
- *A. Henry, K. H. Sandhage, PCT/U.S. Patent Application

♦ High melting point and chemical compatibility (T_{Solidus} = 2,800°C, well above superalloys; tie line between ZrC and W)





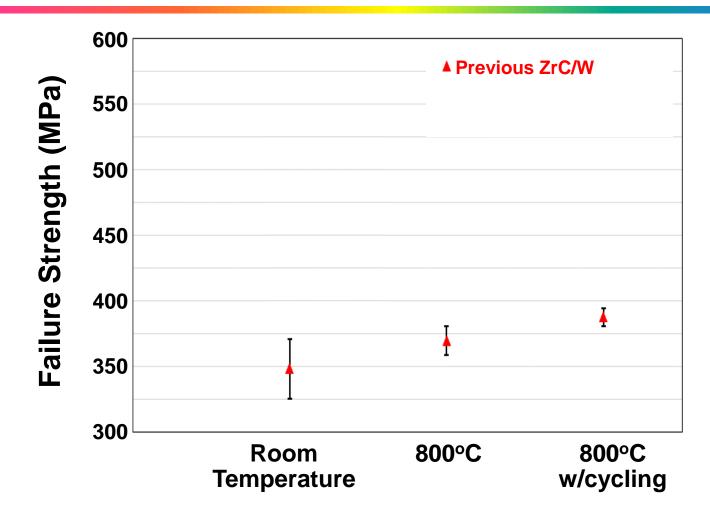


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- ♦ Retention of stiffness and strength at 800°C (E \geq 28x10° psi/193 GPa; $\sigma_F \geq 50x10^3$ psi/350 MPa at RT and at 800°C)

- Y.-W. Zhao, et al., "Microstructure and Properties of ZrC-W Composite Fabricated by Reactive Infiltration of Zr₂Cu into WC/W Preform," *Mater. Chem. Phys.*, 153, 17-22 (2015)
- S. Zhang, et al., "Microstructure and Properties of W-ZrC Composites Prepared by the Displacive Compensation of Porosity (DCP) Method," *J. Alloys Compounds*, 509, 8327-8332 (2011)
- Y.-W. Zhao, et al., "Microstructure and Mechanical Properties of ZrC-W Matrix Composites Prepared by Reactive Infiltration at 1300°C," *Int. J. Refr. Metals Hard Metals*, 37, 40-44 (2013)
- W. D. Callister, *Materials Science and Engineering An Introduction*, 6th Edn., John Wiley & Sons, 2003
- http://www.refractories.saint-gobain.com/hexoloy/hexoloy-grades

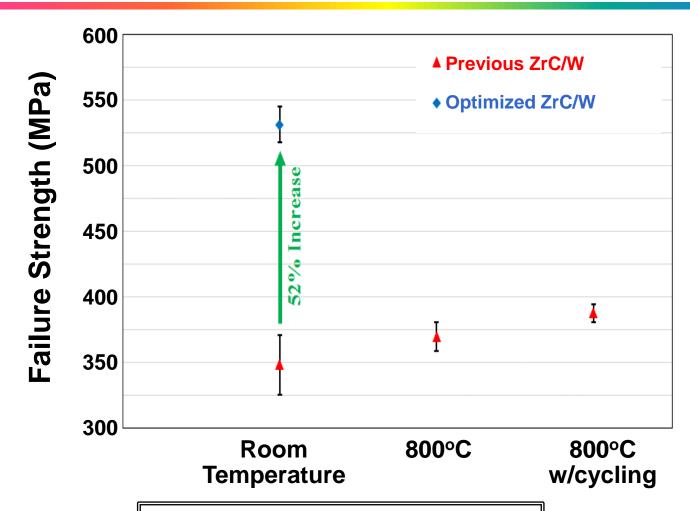


Failure Strength of Current Optimized ZrC/W





Failure Strength of Current Optimized ZrC/W



Average RT Failure Strength: 531 ± 14 MPa; 77.0 ± 2 ksi



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- ◆ Enhanced toughness w.r.t. conventional monolithic ceramics (K_{1C} = 9.4 ± 2.3 MPa⋅m^{1/2} vs. ≤ 0.8 MPa⋅m^{1/2} for Pyrex, ≤ 1.4 MPa⋅m^{1/2} for concrete, ≤ 4.8 MPa⋅m^{1/2} for Hexoloy SiC)

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- ◆ Thermal expansion match (W: 4.5x10⁻⁶/°C 9.2x10⁻⁶/°C from RT 2700°C; ZrC: 4.0x10⁻⁶/°C 10.2x10⁻⁶/°C from RT 2700°C)

- Y. S. Touloukian, R. K. Kirby, R. E. Taylor, P. D. Desai, *Thermal Expansion: Metallic Elements and Alloys*, *Thermophysical Properties of Matter.* Vol. 12. Plenum Press, New York, NY, 1975
- Y. S. Touloukian, R. K. Kirby, R. E. Taylor, PT. Y. R. Lee, *Thermal Expansion:*Nonmetallic Solids, *Thermophysical Properties of Matter*. Vol. 13. Plenum Press, New York, NY, 1977



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- High thermal conductivity (κ = 66.0 W/m-K at 800°C vs. 22.1 W/m-K for IN740H, 24.4 W/m-K for H230)
- http://www.specialmetals.com/files/PCC%20EG%20740H%20White%20Paper.pdf
- http://www.hightempmetals.com/techdata/hitempHaynes230data.php
- A. Sommers, et al., "Ceramics and Ceramic Matrix Composites for Heat Exchangers in Advanced Thermal Systems – A Review," Appl. Thermal Eng., 30, 1277-1291 (2010)
- D.-M. Liu, B.-W. Lin, "Thermal Conductivity in Hot-Pressed Silicon Carbide," *Ceram. Int.*. 22, 407-414 (1996)
- K. Watari, et al., "Effect of Grain Boundaries on Thermal Conductivity of Silicon Carbide Ceramic at 5 to 1300 K," *J. Am. Ceram. Soc.*, 86 (10) 1812-1814 (2003)



◆ Thermal shock resistance and thermal cyclability (ZrC/W nozzles have survived >10³ °C/sec heatup to 2500°C in a Pi-K rocket test; thermal cycling at 10°C/min from RT to 800°C has not resulted in a decrease in fracture strength at 800°C)

[•] M. B. Dickerson, P. J. Wurm, J. R. Schorr, W. P. Hoffman, E. Hunt, K. H. Sandhage, "Near Net-Shaped, Ultra-High Melting, Recession-Resistant Rocket Nozzles Liners via the Displacive Compensation of Porosity (DCP) Method," *J. Mater. Sci.*, 39 (19) 6005-6015 (2004)



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- Corrosion resistance
 (Purification of the molten MgCl₂-KCl salt, and the addition of 50 ppm CO to the sCO₂ with a Cu layer on the ZrC/W surface,
 - have rendered ZrC/W composites resistant to corrosion at 750°C; PCT/U.S. patent application)

• K. H. Sandhage, "Method for Enhancing Corrosion Resistance of Oxidizable Materials and Components Made Therefrom," *PCT/U.S. Patent Application*, 2017; *U.S. Provisional Patent Application*, 2016.



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- ◆ Cost-effective fabrication of ZrC/W-based HEX plates (Scalable, low-cost forming and shape/size-preserving DCP reaction processing of ZrC/W-based plates with tailorable channels and headers for HEXs; PCT/U.S. patent application⁴)



[•] K. H. Sandhage, et al., U.S. Patents No. 6,833,337, No. 6,598,656, No. 6,407,022.

A. Henry, K. H. Sandhage, "Methods for Manufacturing Ceramic and Ceramic Composite Components and Components Made Thereby," *PCT/U.S. Patent* Application, 2017; U.S. Provisional Patent Application, 2016.

Project Objectives

 To design a robust ZrC/W-based heat exchanger with effectiveness and pressure drop values acceptable for the NREL test facility







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- ◆ To demonstrate scalable methods for:
 - fabricating thin (≤3 mm) channeled ZrC/W-based HEX plates with integral headers
 - bonding such plates into HEX stack assemblies connected to Ni alloy tubes







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 - bonding such plates into HEX stack assemblies connected to Ni alloy tubes
- To develop a manufacturing pathway for, and determine the cost of, a 2 MW_{th} ZrC/W-based heat exchanger for Phase 3 of the Gen 3 CSP program







Thrusts and Expertise

Processing

(Tasks 1, 2)

Sandhage,

Trumble,

Wildberger

Areas of Expertise:

- Ceramic forming
- Thermal processing of ceramics
- Reactive melt infiltration
- Near net-shape processing
- Joining
- High-temperature corrosion
- Modeling and design of components for high-temperature thermal systems
- Scale up of manufacturing processes

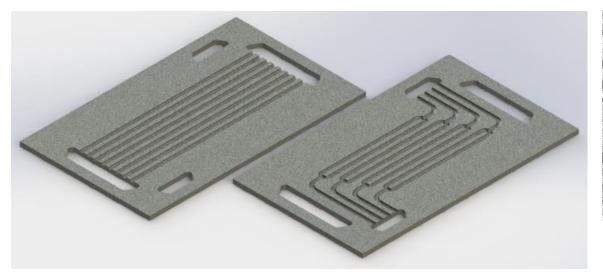
Performance (Tasks 3,4) Henry, Wildberger, Sandhage

Scale Up (Task 5) Wildberger, Henry, Sandhage

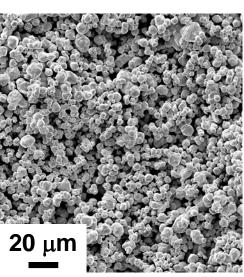
Manufacturing of ZrC/W HEX Plates

Channeled Porous WC Preform Plate

Fabricate porous WC preform plates



Schematic illustrations of porous WC preform plates



Secondary electron image of a fractured cross-section



Manufacturing of ZrC/W HEX Plates

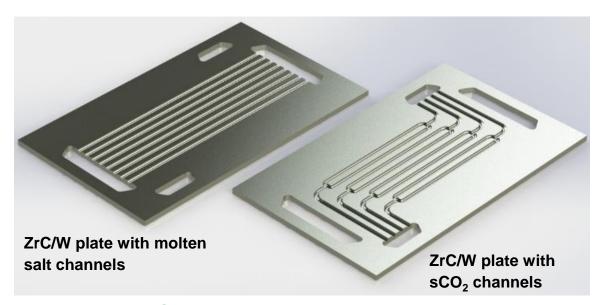
Channeled Porous WC Preform Plate

Fabricate porous WC preform plates

Reactive Conversion

Generate net-size dense ZrC/W plates via DCP process

Channeled ZrC/W Plate

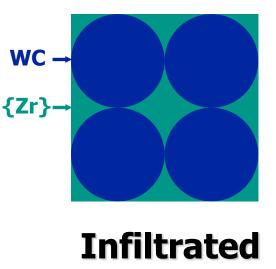


Schematic illustrations of dense-wall ZrC/W HEX plates



Displacive Compensation of Porosity

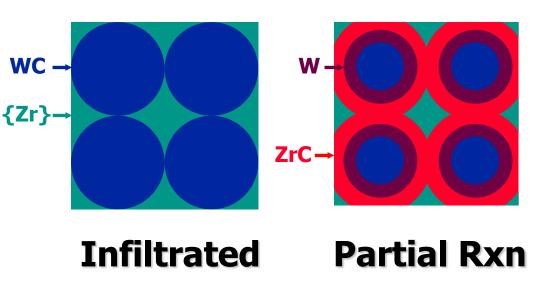
$$WC(s) + \{Zr\}$$





Displacive Compensation of Porosity

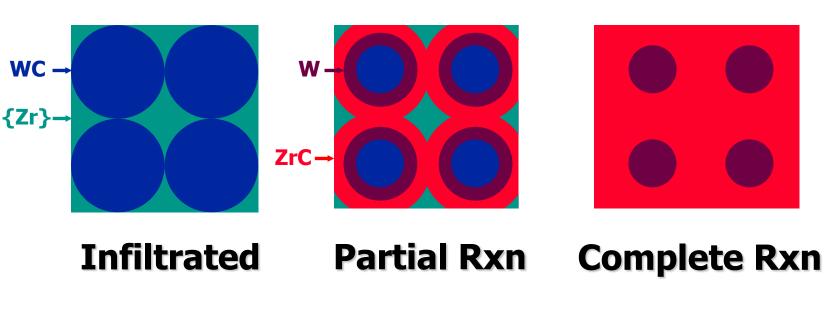
$$WC(s) + {Zr} => ZrC(s) + W(s)$$





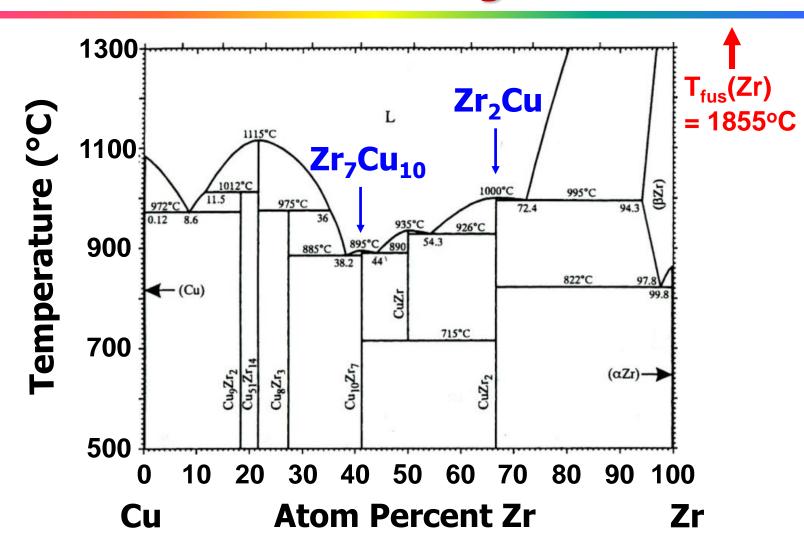
Displacive Compensation of Porosity

$$WC(s) + \{Zr\} => ZrC(s) + W(s)$$
where $V_m[ZrC + W] = 2.01V_m[WC]$





Cu-Zr Phase Diagram



D. Arias, J. P. Abriata, *Bull. Alloy Phase Diagrams*, 11 (5) 452 (1990).

Melt Preparation and Infiltration Equipment



Cold-wall, Induction-heated Melt Infiltration System

- A. Intermediate oil-based HEX for cooling of the Cu induction coils (coupled to a closed chilled water loop)
- B. Oil and water collector systems
- C. Antechamber
- D. Actively-cooled universal ram
- E. Melt box (with induction coils for heating WC preforms and the Zr-Cu melt)
- F. Pressure release valve
- G. Pipe for venting of melt box



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Current ZrC/W-based HEX Plates

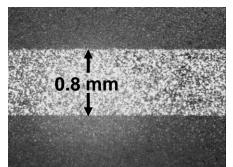


Dense channeled ZrC/W plate generated by shape/size-preserving reactive melt infiltration (DCP process) of a machined porous WC plate



Thinner ZrC/W-based HEX Plates

- The fabrication of thinner (< 3 mm) ZrC/W plates will be examined by:
 - tape casting



Optical micrograph of a cross-section of a multilayer B₄C/B₄C-TiO₂ composite produced by tape casting of layers of B₄C and B₄C-TiO₂, drying, stacking of alternating layers, and then thermal treatment (Trumble, et al.)

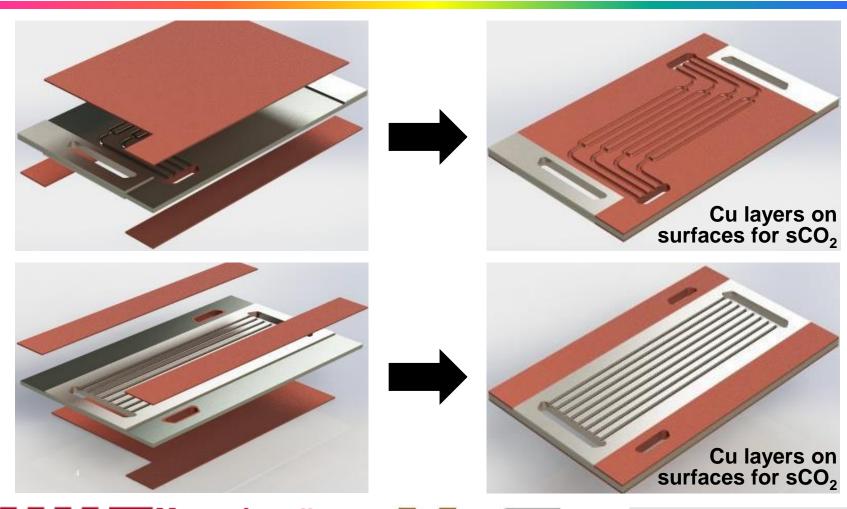
uniaxial pressing



Photograph of a thin (1.7 mm) rigid porous WC plate produced by uniaxial pressing of a WC/binder mixture and then thermal treatment (Sandhage, et al.)

UNIVERSITY

Diffusion Bonding of Cu Layers

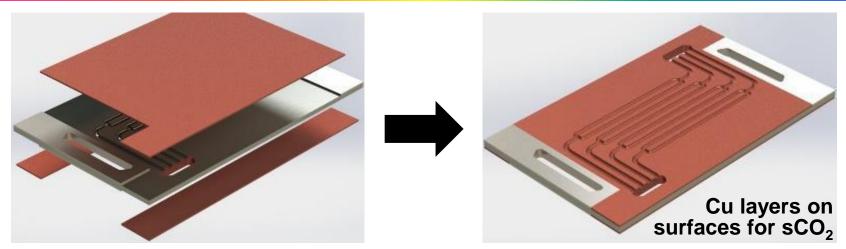








Diffusion Bonding of Cu Layers



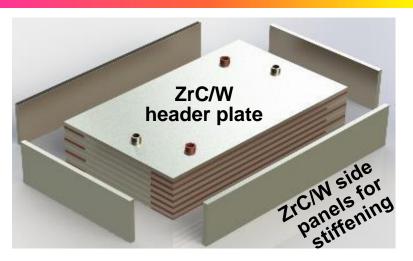




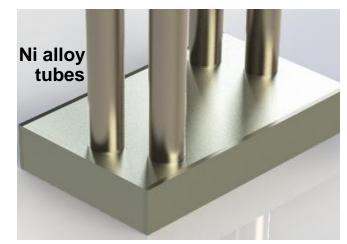




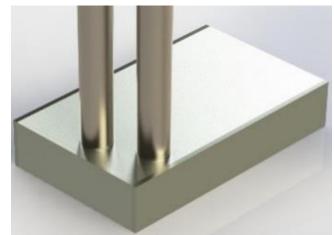
Diffusion Bonding of HEX Assembly







Gas pressure test assembly (inlet tubes only)









HEX Design and Performance Modeling

- ◆ Standard methods for modelling convection (including compressibility) at 750°C (far from the CO₂ critical point) will be used:
 - Reynold's Averaged Navier Stokes equations
 - k-omega model for turbulent sCO₂ flow







HEX Design and Performance Modeling

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 - k-omega model for turbulent sCO₂ flow
- ◆ FLUENT and/or COMSOL software will be used to model steady-state flow through the HEX channels for each fluid to calculate pressure drops
- ◆ The geometries and dimensions of the HEX channels and vias will be tailored to simultaneously optimize the effectiveness, pressure drops, and thermomechanical reliability







Scale Up of Manufacturing

- Work will be conducted to evaluate scalable:
 - WC preform plate forming (casting, compaction, stamping) and heat treatments (drying, sintering)
 - ZrC/W plate production (melt infiltration)
 - Diffusion bonding (metal layers, plate stacks)
 - Joining of Ni alloy tubes to header plates
- VPE capabilities and expertise (thermal treatments, bonding) fit well with much of this scale-up work
- Additional required equipment, facilities, and partners or vendors will be identified







Summary

◆ ZrC/W cermets provide an attractive combination of high-temperature properties relative to state-of-the-art metal alloys







Summary

- ZrC/W cermets provide an attractive combination of high-temperature properties relative to state-of-the-art metal alloys
- ◆ Low-cost ceramic forming methods, coupled with a shape/size-preserving reactive melt infiltration (DCP) process, can be used to fabricate dense ZrC/W HEX plates with tailorable channel patterns
- Scalable strategies for manufacturing robust ZrC/Wbased HEX assemblies have been identified







Summary

- ZrC/W cermets provide an attractive combination of high-temperature properties relative to state-of-the-art metal alloys
- ◆ Low-cost ceramic forming methods, coupled with a shape/size-preserving reactive melt infiltration (DCP) process, can be used to fabricate dense ZrC/W HEX plates with tailorable channel patterns
- ◆ Scalable strategies for manufacturing robust ZrC/Wbased HEX assemblies have been identified
- ♦ Work with VPE and other (TBD) partners/vendors will be conducted to develop a manufacturing pathway to a 2 MW_{th} ZrC/W HEX for Phase 3 of the Gen3 CSP program







Questions? Suggestions?





